

Amendments to the Specification

Kindly replace paragraph [0053] with the following amended paragraph:

[0053] As shown in FIG. 4A, the first dielectric layer 220 is deposited on a separate substrate (hereinafter referred to as “first substrate”) 210. The first dielectric layer 220 will serve to electrically insulate the first electrode 230 from the first substrate 210 and to facilitate the deposition of the first electrode 230. The substrate 210 may be an insulating material such as SiO₂ and $[[\text{Al}_2\text{O}_3]]$ Al₂O₃, but is not limited thereto.

Kindly replace paragraph [0053] with the following amended paragraph:

[0072] Meanwhile, in another embodiment of the present invention, rather than completely removing the first substrate 210 as shown in FIG. 4J, a more stable packaging may be realized by leaving a film of the first substrate 210 of a predetermined thickness, as shown in FIG. $[[6]]$ 7. The thickness of the first substrate film 210 may be within 3 μm and is determined in accordance with a desired degree of stabilization of the element and a degree of deterioration of the resonance due to the addition of the substrate film. As described above, the integration can be performed on the PCB with packaging at a unit element level.